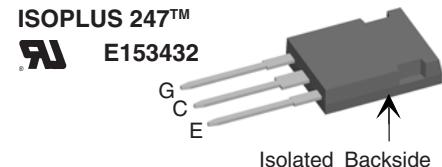
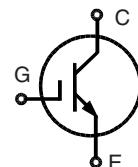


NPT³ IGBT

in ISOPLUS 247™

I_{C25} = 95 A
V_{CES} = 1200 V
V_{CE(sat) typ.} = 2.1 V



G = Gate C = Collector E = Emitter

IGBT

Symbol	Conditions	Maximum Ratings		
V _{CES}	T _{VJ} = 25°C to 150°C	1200	V	
V _{GES}		± 20	V	
I _{C25}	T _C = 25°C	95	A	
I _{C90}	T _C = 90°C	60	A	
I _{CM}	V _{GE} = ±15 V; R _G = 22 Ω; T _{VJ} = 125°C RBSOA, Clamped inductive load; L = 100 μH	100	A	
V _{CEK}		V _{CES}		
t _{sc} (SCSOA)	V _{CE} = 900 V; V _{GE} = ±15 V; R _G = 22 Ω; T _{VJ} = 125°C non-repetitive	10	μs	
P _{tot}	T _C = 25°C	375	W	

Symbol	Conditions	Characteristic Values		
		(T _{VJ} = 25°C, unless otherwise specified)	min.	typ.
V _{CE(sat)}	I _C = 60 A; V _{GE} = 15 V; T _{VJ} = 25°C T _{VJ} = 125°C	2.1 2.5	2.7 V	V
V _{GE(th)}	I _C = 2 mA; V _{GE} = V _{CE}	4.5	6.5	V
I _{CES}	V _{CE} = V _{CES} ; V _{GE} = 0 V; T _{VJ} = 25°C T _{VJ} = 125°C	0.1	0.1 mA mA	
I _{GES}	V _{CE} = 0 V; V _{GE} = ± 20 V		200 nA	
t _{d(on)} t _r t _{d(off)} t _f E _{on} E _{off}	Inductive load, T _{VJ} = 125°C V _{CE} = 600 V; I _C = 60 A V _{GE} = ±15 V; R _G = 22 Ω	80 50 680 30 7.2 4.8	ns ns ns ns mJ mJ	
C _{ies}		3.8	nF	
Q _{Gon}		350	nC	
R _{thJC}			0.33 K/W	
R _{thJH}		0.66	K/W	

Features

- NPT³ IGBT
 - low saturation voltage
 - positive temperature coefficient for easy paralleling
 - fast switching
 - short tail current for optimized performance in resonant circuits
- ISOPLUS 247™ package
 - isolated back surface
 - low coupling capacity between pins and heatsink
 - high reliability
 - industry standard outline

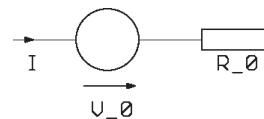
Applications

- single switches and with complementary free wheeling diodes
- choppers
- phaselegs, H bridges, three phase bridges e.g. for
 - power supplies, UPS
 - AC, DC and SR drives
 - induction heating

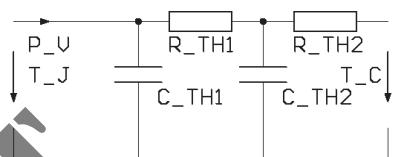
Component

Symbol	Conditions	Maximum Ratings		
T_{VJ}		-55...+150	$^{\circ}\text{C}$	
T_{stg}		-55...+125	$^{\circ}\text{C}$	
V_{ISOL}	$I_{ISOL} \leq 1 \text{ mA}; 50/60 \text{ Hz}$	2500	V~	
F_c	mounting force with clip	20...120	N	

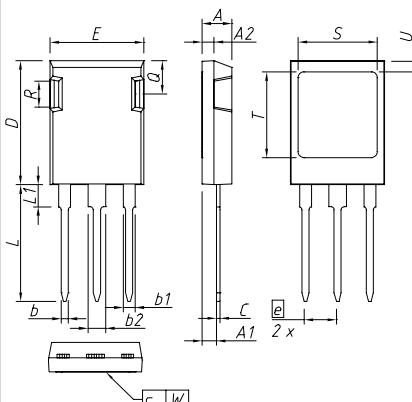
Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
C_p	coupling capacity between shorted pins and mounting tab in the case	30		pF
Weight		6		g

Equivalent Circuits for Simulation**Conduction**

IGBT (typ. at $V_{GE} = 15 \text{ V}$; $T_J = 125^{\circ}\text{C}$)
 $V_0 = 0.99 \text{ V}$; $R_0 = 25 \text{ m}\Omega$

Thermal Response

IGBT (typ.)
 $C_{th1} = 0.13 \text{ J/K}$; $R_{th1} = 0.06 \text{ K/W}$
 $C_{th2} = 0.32 \text{ J/K}$; $R_{th2} = 0.27 \text{ K/W}$

ISOPLUS247™ OUTLINE

DIM.	MILLIMETER		INCHES	
	MIN	MAX	MIN	MAX
A	4,83	5,21	0,190	0,205
A1	2,29	2,54	0,090	0,100
A2	1,91	2,16	0,075	0,085
b	1,14	1,40	0,045	0,055
b1	1,91	2,15	0,075	0,085
b2	2,92	3,20	0,115	0,126
C	0,61	0,83	0,024	0,033
D	20,80	21,34	0,819	0,840
E	15,75	16,13	0,620	0,635
e	5,45 BSC		0,215 BSC	
L	19,81	20,60	0,780	0,811
L1	3,81	4,38	0,150	0,172
Q	5,59	6,20	0,220	0,244
R	4,32	4,85	0,170	0,191
S	13,21	13,72	0,520	0,540
T	15,75	16,26	0,620	0,640
U	1,65	2,03	0,065	0,080
W	-	0,10	-	0,004

The convex bow of substrate is typ. < 0.04 mm over plastic surface level of device bottom side
This drawing will meet all dimensions requirement of JEDEC outline TO-247 AD except screw hole and except Lmax.

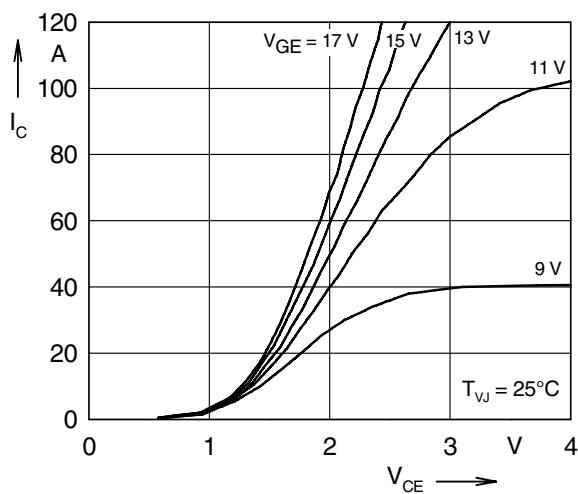


Fig. 1 Typ. output characteristics

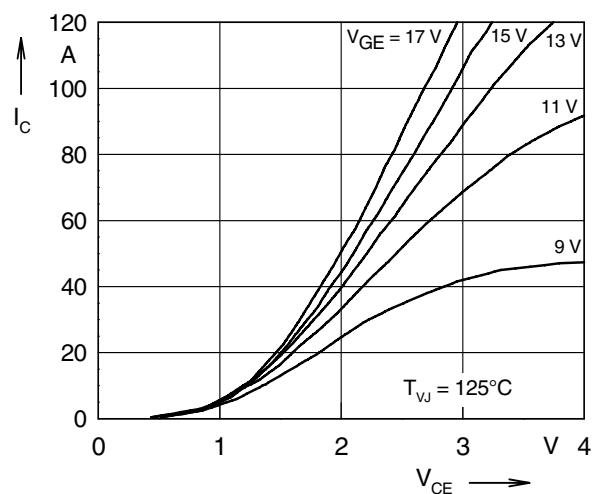


Fig. 2 Typ. output characteristics

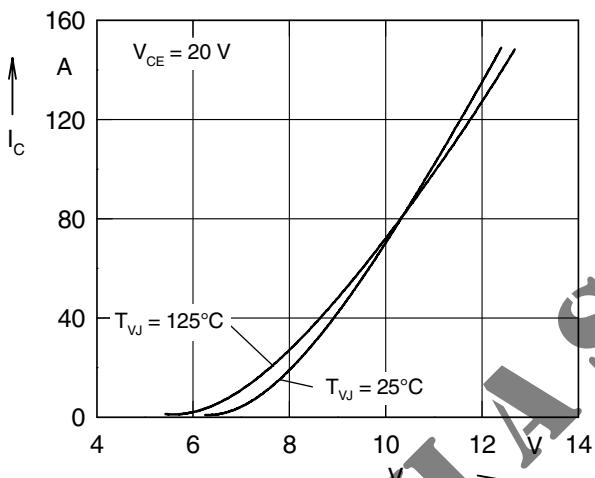


Fig. 3 Typ. transfer characteristics

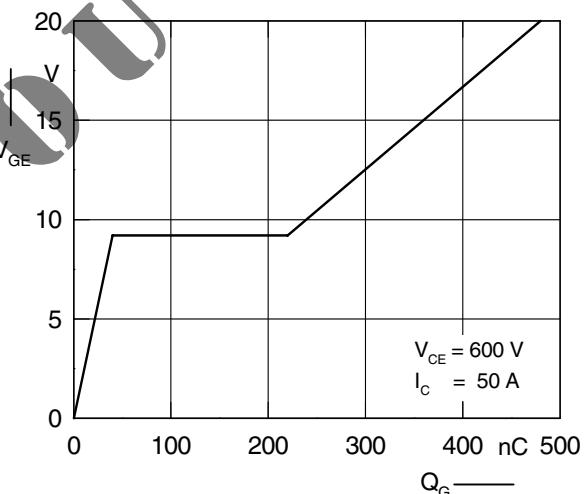


Fig. 4 Typ. turn on gate charge

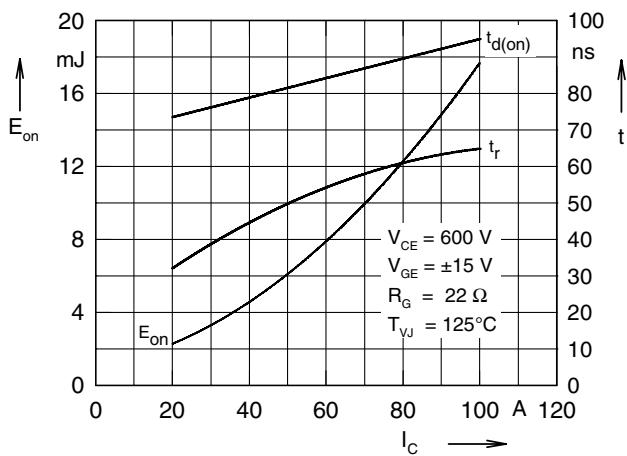


Fig. 5 Typ. turn on energy and switching times versus collector current

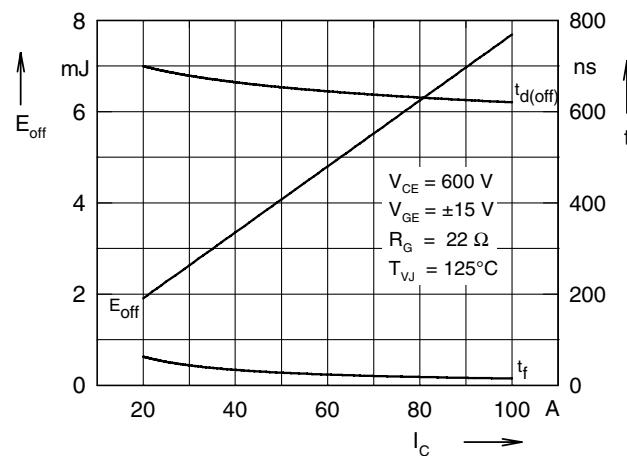


Fig. 6 Typ. turn off energy and switching times versus collector current

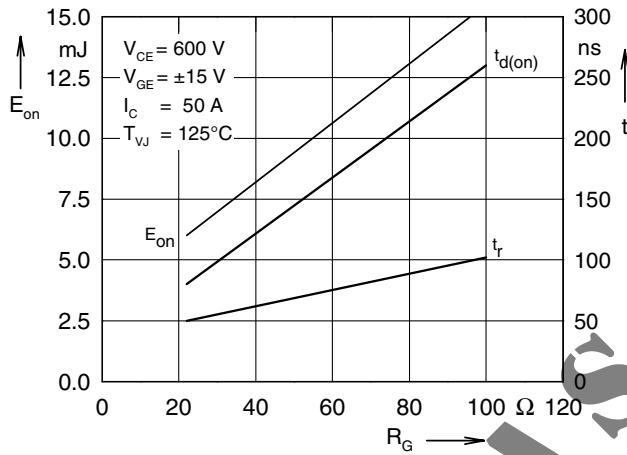


Fig. 7 Typ. turn on energy and switching times versus gate resistor

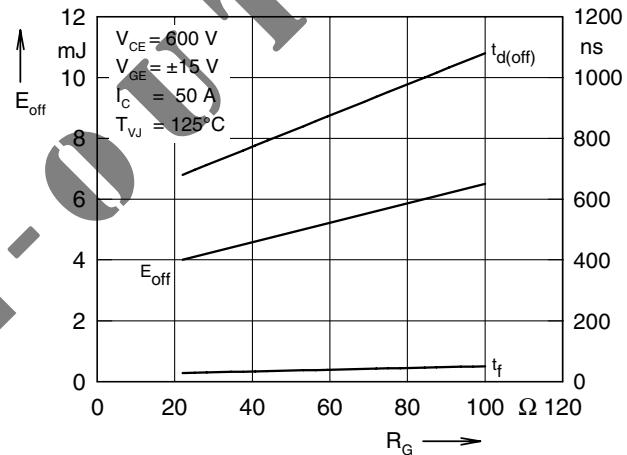


Fig. 8 Typ. turn off energy and switching times versus gate resistor

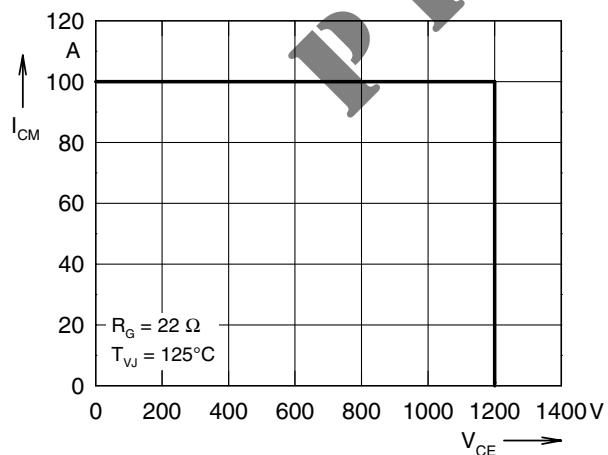


Fig. 9 Reverse biased safe operating area RBSOA

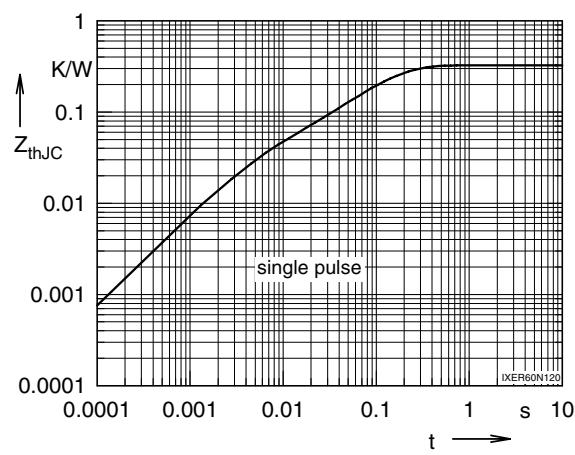


Fig. 10 Typ. transient thermal impedance